TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

TD62703P, TD62703F

6CH HIGH VOLTAGE SOURCE DRIVER

The TD62703P, TD62703F is comprised of six source current Transistor Array. These drivers are specifically designed for fluorescent display applications. For proper operation, the substrate (SUB) must be

connected to the most negative voltage.

FEATURES

Input resistor

- : V_{CC} , $V_{OUT} = 60V$ (Min.) High output voltage
- Output current (single output) : $I_{OUT} = -50 \text{mA}$ (Max.)
 - : $R_{IN} = 2.7 k \Omega$
- Package type-P : DIP-14 pin
- Package type-F : SOP-14 pin

PIN CONNECTION (TOP VIEW)



SCHEMATICS (EACH DRIVER)



TD62703P DIP14-P-300-2.54 TD62703F REPERE SOP14-P-225-1.27

Weight DIP14-P-300-2.54 : 1.11g (Typ.) SOP14-P-225-1.27 : 0.16g (Typ.)

(Note) The input and output parasitic diodes cannot be used as clamp diodes.

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- 961001EBA:
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MAXIMUM RATINGS (Ta = 25° C)

CHARACTERISTIC	C	SYMBOL	RATING	UNIT	
Supply Voltage		V _{SUB}	V _{CC} – 60	V	
Output Sustaining Volt	tage	Vout	V _{CC} – 60	V	
Input Voltage		VIN	- 30~0.5	V	
Output Current		Ιουτ	- 50	mA / ch	
Input Current		liN	10	mA	
Power Dissipation	Р	D_{-} (Neta 2)	1.0	w	
	F	P _D (Note 2)	0.625 (Note 1)		
Operating Temperature	e	T _{opr}	- 40~85	°C	
Storage Temperature		T _{stg}	- 55~150	°C	

(Note 1) On Glass Epoxy PCB (50×50×1.6mm Cu 50%)
(Note 2) Delated above 25°C in the proportion 8.0mW/°C (P Type), 5.0mW/°C (F Type).

RECOMMENDED OPERATING CONDITIONS ($Ta = -40 \sim 85^{\circ}C$)

CHARACTERISTI	с	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Supply Voltage		V _{SUB}		VOUT		- 55	V
Output Sustaining Voltage VC		Vout		0	—	V _{SUB}	V
Output Current		Ιουτ	V _{CC} = 0V	0	—	- 40	mA / ch
Input Voltage		VIN		0		- 7.0	V
Power Dissipation	Р	D-	_	—	—	0.36	w
	F	PD	On PCB (Note)	—	_	0.325	vv

(Note) On Glass Epoxy PCB ($50 \times 50 \times 1.6$ mm Cu 30%)

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACT	ERISTIC	SYMBOL	TEST CIR- CUIT	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Output Leakage	e Current	ICEX	1	V _{CC} = 0V, V _{IN} = 0V V _{OUT} = - 55V	-	_	- 100	μΑ
Collector-Emitte Saturation Volt		V _{CE (sat)}	2	I _{IN} = - 1mA, I _{OUT} = -40mA		—	- 2.5	V
DC Current Transfer Ratio		h _{FE}	2	$V_{CE} = -5.0V, I_{OUT} = -40mA$	100	—	_	Ι
linnut Current 🛏	Output On	VIN (ON)	3	$V_{CC} = 0V, V_{IN} = -5.1V$	_	– 1.7	- 2.4	mA
	Output Off	VIN (OFF)		—		_	10	μA
Linnut Voltage —	Output On	VIN (ON)	4	V _{CC} = 0V	- 3.0	_		V
	Output Off	VIN (OFF)			_	_	-0.44	
Turn-On Delay	P			$V_{CC} = 0V$, $V_{SUB} = V_{OUT} = -55V$ $R_L = 1.4k\Omega$, $C_L = 15pF$		1	—	μs
	F	ton			_	0.5	_	
Turn-Off Delay	P	+ o = =			_	2	_	
	F	^t OFF			_	1	—	μ s

TEST CIRCUIT

1. ICEX



۷сс

VSUB

lout

VIN

IN (ON)

IN (OFF)

- $V_{CC} + V_{CE (sat)}$ $V_{UT} + V_{UT}$ $V_{SUB} + FE = \frac{I_{OUT}}{I_{IN}}$
- 4. VIN (ON), VIN (OFF)

2. VCE (sat), hFE



3. IN (ON), IN (OFF)

5. t_{ON}, t_{OFF}





PRECAUTIONS for USING

Utmost care is necessary in the design of the output line, V_{CC} and GND (SUB) line since IC may be destroyed due to short-circuit between outputs, air contamination fault, or fault by improper grounding.





OUTLINE DRAWING DIP14-P-300-2.54

Unit : mm





OUTLINE DRAWING

SOP14-P-225-1.27



Weight : 0.16g (Typ.)